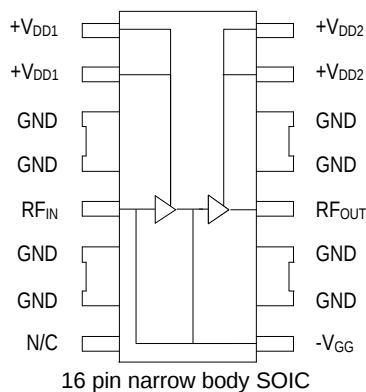


Applications

Two-Way Paging
Wireless Modems
Cordless Telephones
Telemetry
900 MHz ISM

Features

- Class AB Bias
- 800 to 1000 MHz Operation
- Single Element Input Match
- Single Element Output Match
- Small Size — 16 Pin Narrow Body SOIC Plastic Package
- Self-Aligned MSAG®-Lite MESFET Process
- Guaranteed Stability and Ruggedness



Typical 3.6 Volt Performance

30.4 dBm Power Output
23.4 dB Power Gain
54% Power Added Efficiency
All Harmonics < -30 dBc

MAXIMUM RATINGS (T_A = 25 °C unless otherwise noted)

Rating	Symbol	Value	Unit
DC Supply Voltage (Pins 1, 2, 15, 16)	V _{DD}	10	Vdc
DC Gate Bias Voltage (Pin 9)	V _{GG}	-5	Vdc
RF Input Power	P _{IN}	15	mW
Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-40 to +150	°C

ELECTRICAL CHARACTERISTICS V_{DD}=3.6 V, P_{IN}=7 dBm, T_S=50 °C (Note 1), Output externally matched to 50 Ω System.

Characteristic	Symbol	Typical	Unit
Frequency Range	f	900 to 942	MHz
Output Power (P _{IN} = 7 dBm, V _{GG} adjusted for desired output power)	P _{OUT}	1.1	W
Power Gain (P _{OUT} = 30.4 dBm)	G _P	23.4	dB
Power Added Efficiency	η	54	%
Harmonics (P _{OUT} = 30.4 dBm)	2f _o 3f _o	-38 -31	dBc dBc
Input VSWR (P _{OUT} = 30.4 dBm), 50 Ω Ref.	—	1.3:1	—
Thermal Resistance (Junction of 2 nd stage FET to solder point of pin 11)	R _{TH J-S}	24	°C/W
Load Mismatch (V _{DD} = 5V, VSWR = 10:1)	—	No Degradation in Power Output	
Stability (P _{IN} = -3 to +10 dBm, V _{DD} = 0-5 V, 0 mW < P _{OUT} < 1.1 W, T _S = -40 to +100 °C, Load VSWR = 10:1)	—	All non-harmonically related outputs more than 60 dB below desired signal	

Note 1: T_S is the temperature measured at the soldering point of pin 11, mounted on 60 mil GETEK evaluation board in a free air condition with ambient room temperature T_A=25 °C. The electrical data presented herein was taken with the evaluation board shown in Figures 1 and 6, under room temperature conditions and CW operation, unless otherwise specified.

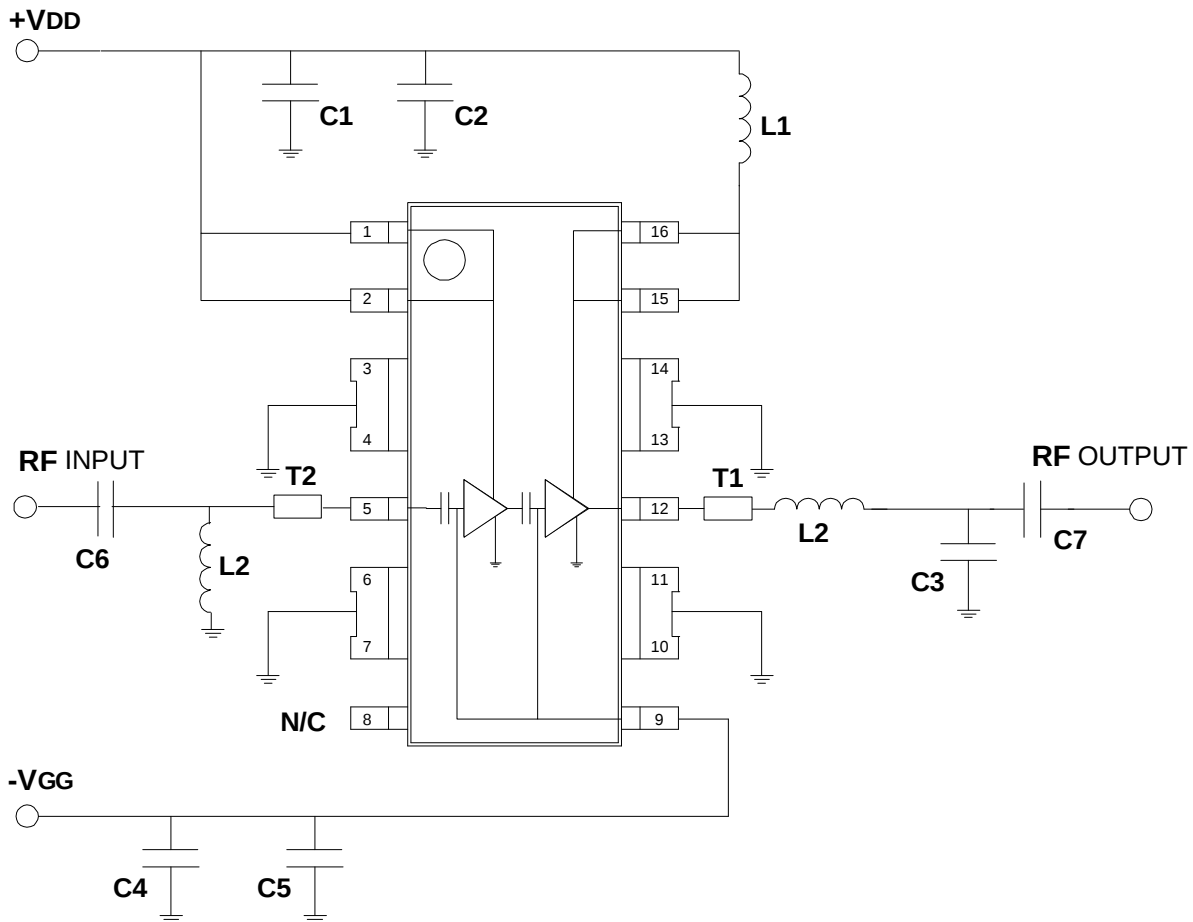
Preliminary Data - Specifications Subject to Change Without Notice

901744 B, December 1998



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APPLICATION INFORMATION



60mil GETEK Board

Figure 1. Evaluation Board Schematic

List of components:

- C1 = C4 = 0.1 μ F Kemet multilayer ceramic chip capacitor (C1206C104K5RAC)
- C2 = C5 = 4700 pF Kemet multilayer ceramic chip capacitor (C0805C472K5RAC)
- C3 = 8.2 pF DLI multilayer ceramic chip capacitor (C11AH7R5B5TXL)
- C6 = C7 = 100 pF DLI multilayer ceramic chip capacitor (DC Block; C11AH101K5TXL)
- L1 = 39 nH Coilcraft chip inductor (1008CS.390XMBB)
- L2 = 8.2 nH Coilcraft chip inductor (1008CT.080XKBB)
- R1 = 100 Ω
- T1 = 0.14" of 50 Ω grounded coplanar waveguide (60 mil GETEK board)
- T2 = 0.16" of 50 Ω grounded coplanar waveguide (60 mil GETEK board)



Component layout and printed circuit board drawing for RF IC evaluation board are shown in Figure 6.

Biasing: Gate bias voltage (V_{GG}) must be applied prior to RF input power and drain bias voltage (V_{DD}). Reverse the sequence when turning the part off — remove the RF input and drain bias before removing gate bias.

TYPICAL CHARACTERISTICS

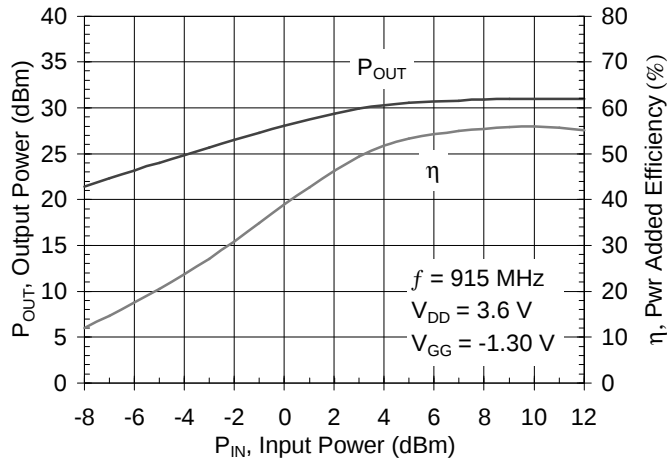


Figure 2. Output power and efficiency vs. input power for a fixed gate bias

Conditions for Figure 2:

Gate bias (V_{GG}) is set for 1.1 W of output power when $P_{IN} = 7 \text{ dBm}$.

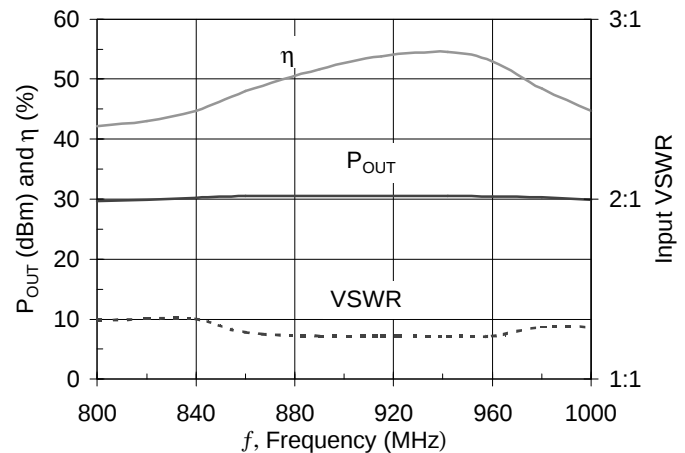


Figure 3. Output power, efficiency and input VSWR vs. frequency

Conditions for Figure 3:

Control voltage (V_{GG}) is adjusted at each frequency to maintain 1.1 W output power. $V_{DD} = 3.6 \text{ V}$, $P_{IN} = 7 \text{ dBm}$.

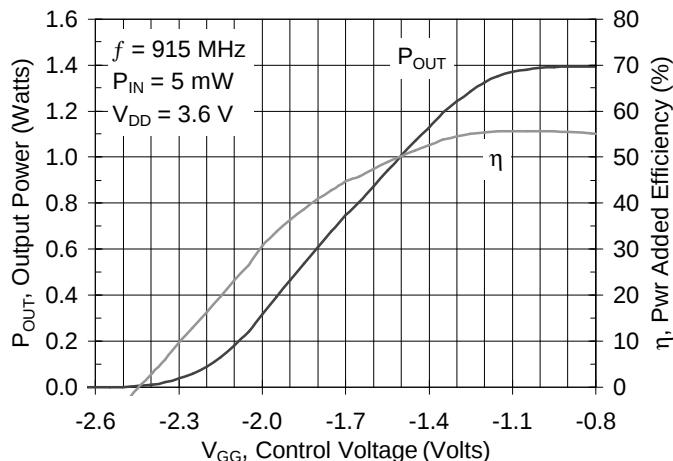


Figure 4. Output power and efficiency vs. control voltage

Conditions for Figure 4:

While keeping supply voltage constant ($V_{DD} = 3.6 \text{ V}$), the output power is controlled by adjusting DC gate bias (V_{GG}).

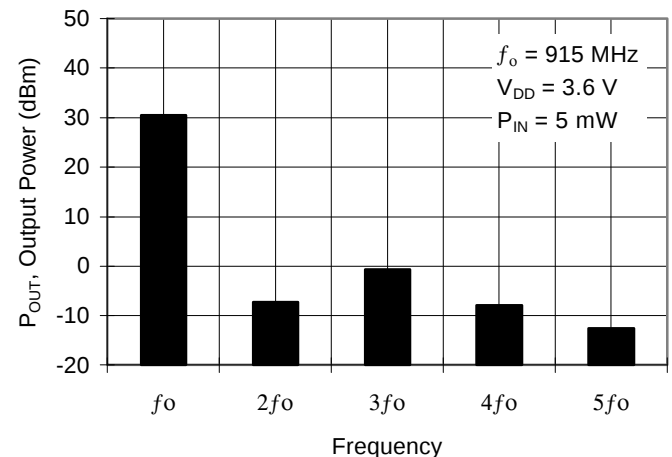
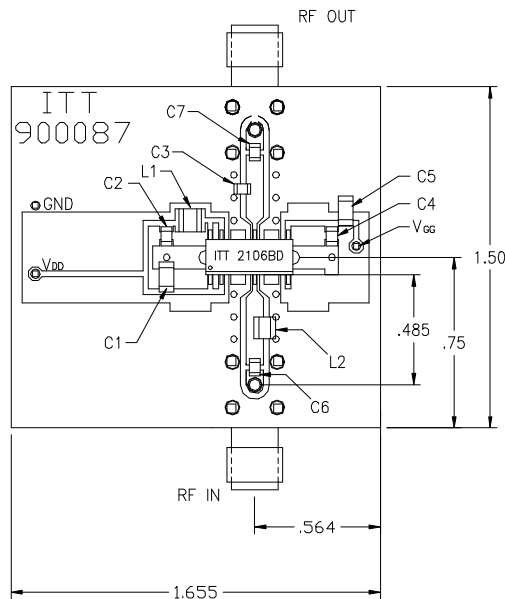
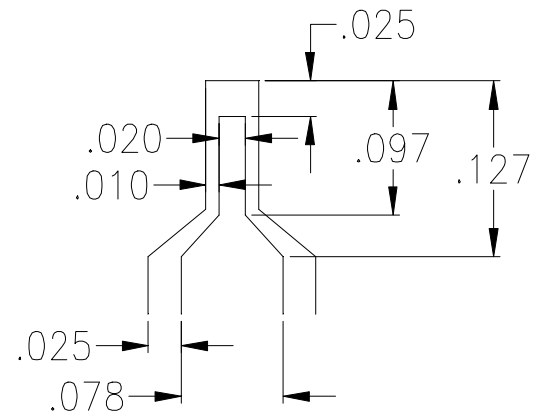


Figure 5. Harmonics

MECHANICAL DATA



Top view



50Ω lead transition

Figure 6. Component layout and printed circuit drawing for evaluation board

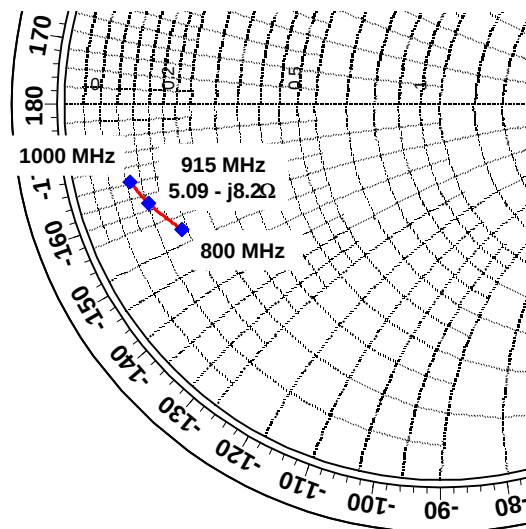


Figure 7. Output match impedance (as seen from pin 12)